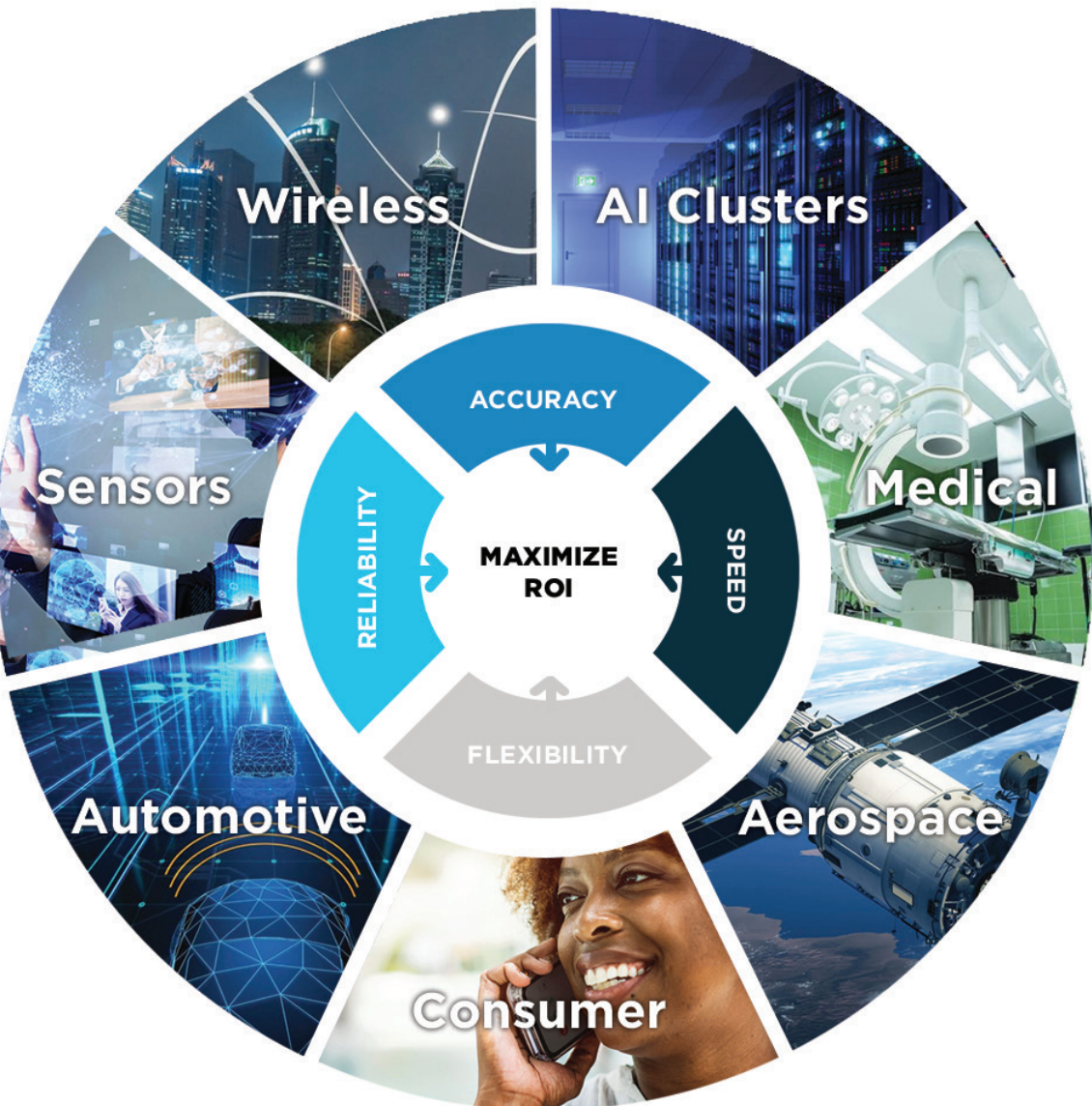


Bringing tomorrow's electronics to life



Bringing tomorrow's electronics to life

mrsi.mycronic.com

North America MRSI Systems 554 Clark Rd., Tewksbury, MA USA 01876 Tel: +1 978 667 9449 sales.mrsi@mycronic.com	Asia MRSI Automation (Shenzhen) Co., Ltd 101, Building B, Han's Innovation Tower, 9018 Beihuan Avenue, Nanshan District, Shenzhen City, Guangdong Province, China 518057 Tel: +86 755 26414155	EMEA Distributor and Demo Center Distek Strumenti & Misure Srl Via Guglielmo Marconi, 15, 80125 Napoli NA, Italy Tel: +39 348 3837815 marco@distek.it
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MRSI Systems (a part of Mycronic Group) is the leading manufacturer of fully automated, high-speed, high-precision, and flexible eutectic and epoxy die bonding systems. We leverage over 40 years of industry expertise in high-accuracy die bonders, active aligners, and fluid dispensers to deliver unparalleled precision and reliability for R&D, NPI, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, silicon photonics, co-packaging optics, and optical imaging products. We provide the most flexible assembly solutions for all packaging levels, including chip-on-wafer (CoW), chip-on-carrier (CoC), PCB, and gold-box packaging. Our commitment to excellence ensures we meet our customers' needs with meticulous attention to detail and 24/7 field support. For more information, visit <https://www.mycronic.com/product-areas/die-bonding/>.

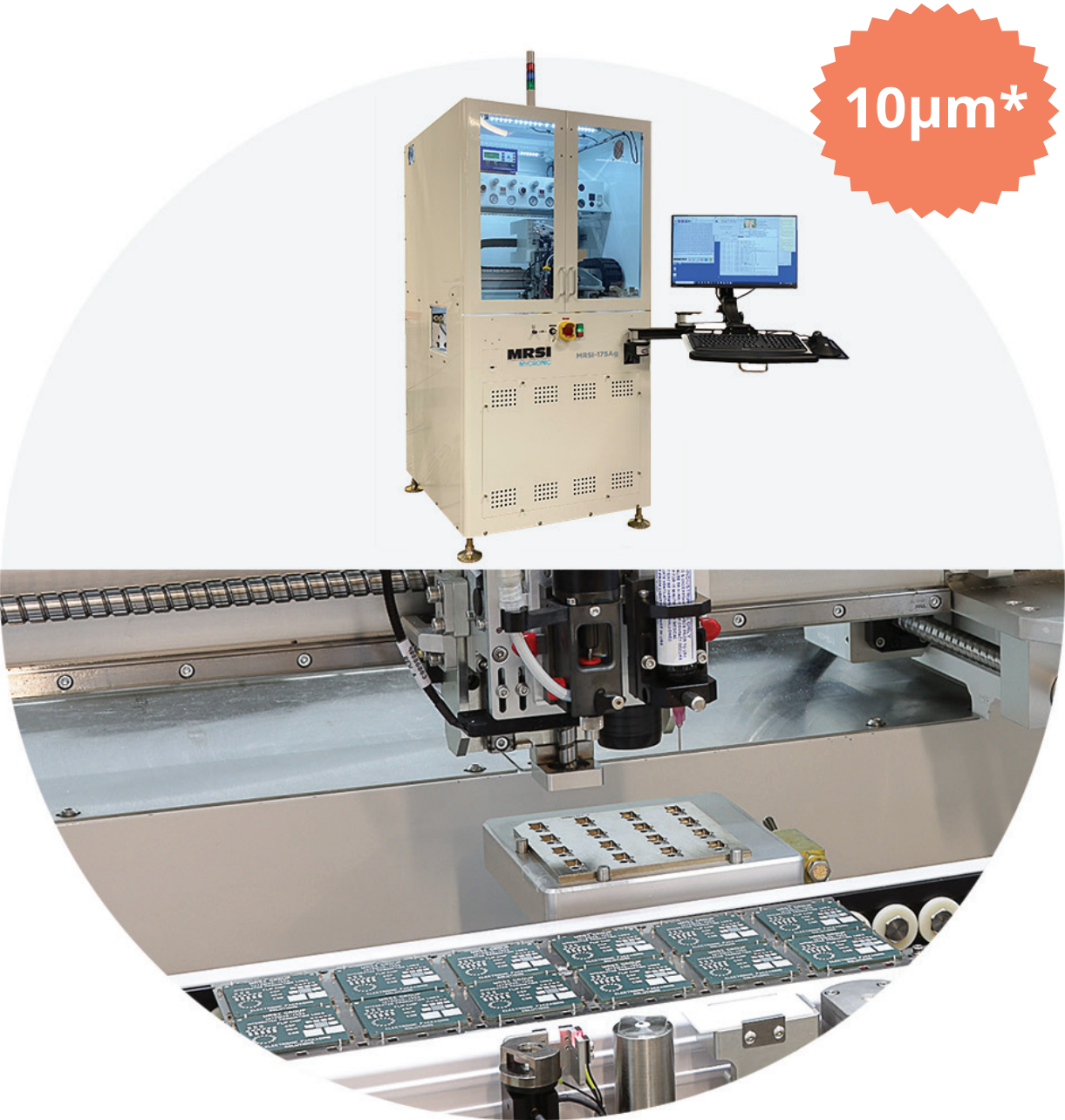
Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic's headquarters are located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Mexico, the Netherlands, Singapore, South Korea, United Kingdom, the United States and Vietnam. Mycronic is listed on Nasdaq Stockholm. www.mycronic.com

Specifications are subject to change without notice.

202607_MRSI-175AGV4



MRSI-175Ag EPOXY DISPENSER



*Available on the MRSI 175Ag+

MRSI Systems has been serving optoelectronic and microelectronic customers for over 40+ years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications are found across a wide range of market segments, such as AI Clusters, Medical, Aerospace, Wireless, Automotive, Sensors, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-pace innovations of critical components for high-growth market segments. The MRSI-175Ag Conductive Epoxy Dispenser handles the most demanding dispensing applications such as semiconductor packaging, microwave & RF modules, multi-chip modules, optical modules, hybrid circuits, sensors, and MEMS.

Our die bonding solutions are built on standardized hardware and software platforms configured to minimize process deviations, reduce NPI cost, deliver long term proven product reliability and supported by our global customer service team. These factors deliver the best financial returns in the industry.



MRSI-175Ag Next Generation Epoxy Dispenser Highly Configurable



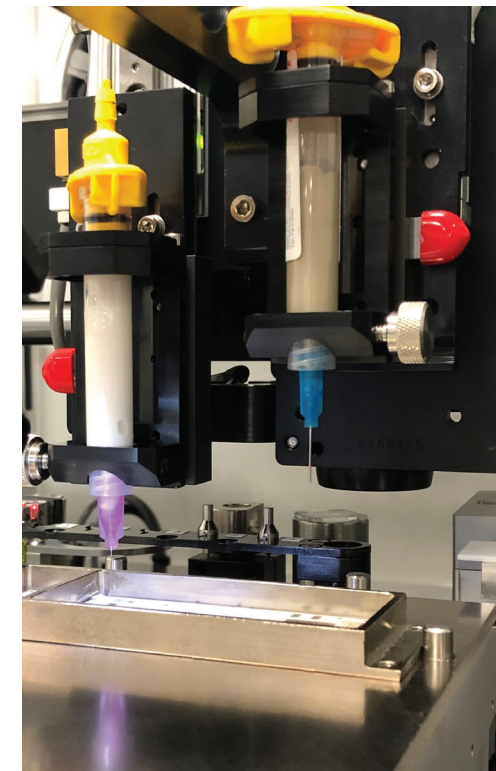
Assembly Technologies

- Underfill
- Epoxy die attach
- Encapsulation
- Multi-pin stamping
- UV epoxy



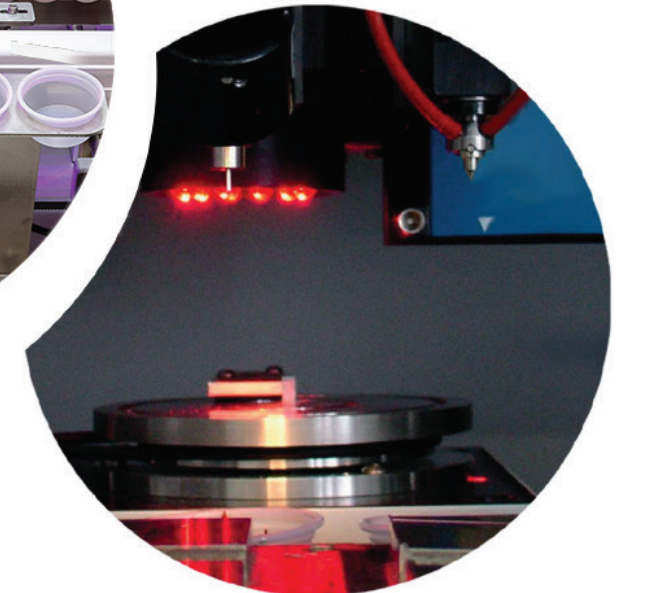
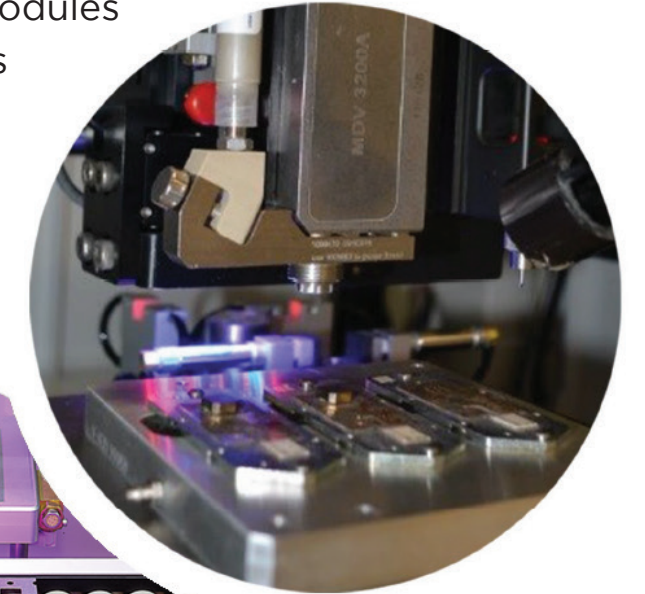
Flexible Dispensing Platform

- Increased capacity at lower cost
- Lower cost of ownership
- Less labor cost
- Higher yields
- Flexibility
- Ultra-high speed
- 35% more energy efficient
- 25µm accuracy (10µm accuracy MRSI-175Ag+ available)



Applications

- Semiconductor packaging
- Microwave & RF modules
- Multi-chip modules
- Optical modules
- Hybrid circuits
- Sensors
- MEMS



Options

- Laser height sensor
- Confocal height sensor
- Conveyor
- Jet
- Stamping
- Real-time video monitoring